



(3583)

2022/06/16

### **Safe Harbor Statement**



- This Presentation contains certain forward-looking statements that are based on current expectations and are subject to known and unknown risks and uncertainties that could cause actual results to differ materially from those expressed or implied by such statements.
- Except as required by law, we undertake no obligation to update any forward –looking statements, whether as a result of new information, future events or otherwise.

# Scientech Corp (3583: TT)



IPO 2013/3/12

Capital NT\$ 811 Million

Chairman H.L. Hsieh

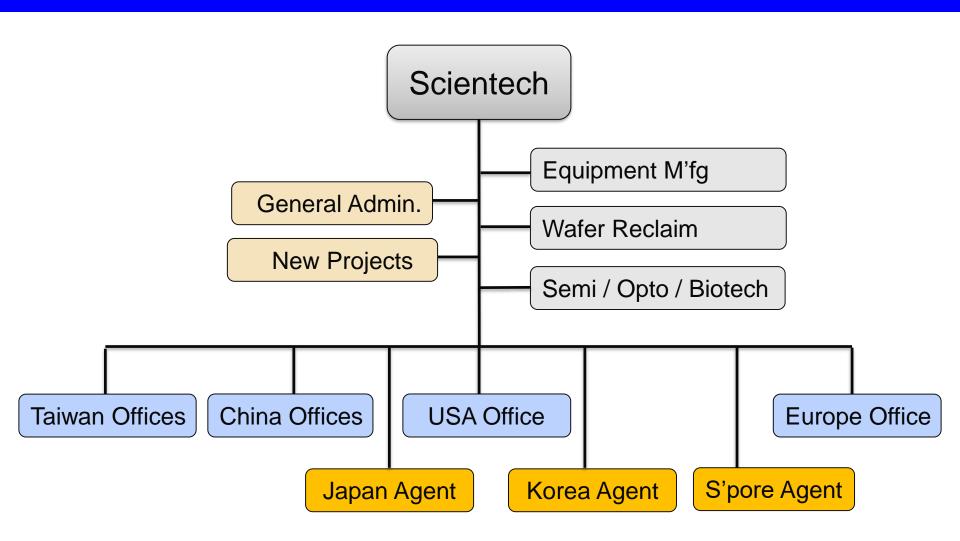
Company

CEO M.T. Hsu

Products Equipment Manufacturing • Wafer Reclaim • Trading(Agent/Distributor)

### **Organization**







#### Business

Overview

**Products** 

Corporate Governance

> Future Prospect

# Business Overview

### **Income Statement**



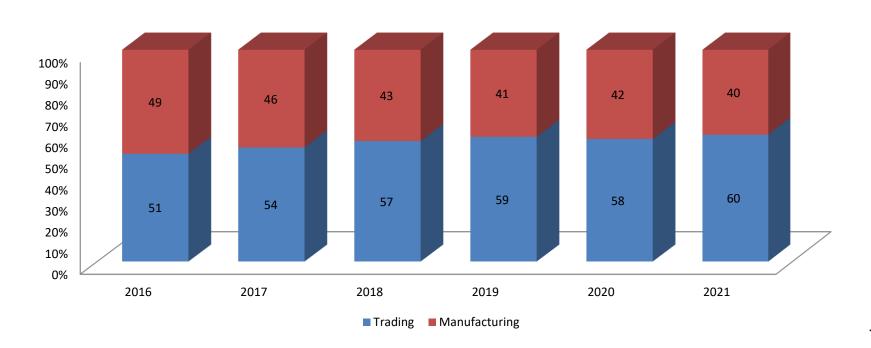
|                           |              |             |       | <u> </u> |       |            |
|---------------------------|--------------|-------------|-------|----------|-------|------------|
| Units: NT \$ M            | 2017         | 2018        | 2019  | 2020     | 2021  | 2022/Q1    |
| Revenues                  | <u>3,539</u> | 3,988       | 3,949 | 3,580    | 4,684 | 1,254      |
| Gross Profit              | <u>1,251</u> | 1,448       | 1,384 | 1,456    | 1,667 | <u>461</u> |
| Operating Expenses        | 829          | 935         | 997   | 991      | 1,112 | 332        |
| Operating Income          | 423          | 514         | 387   | 465      | 555   | 129        |
| Other Income and Expenses | (8)          | 26          | 16    | (76)     | (31)  | 26         |
| Income Before Tax         | 415          | 540         | 403   | 389      | 524   | 155        |
| Net Income                | 328          | 418         | 323   | 305      | 420   | 121        |
| EPS                       | 4.05         | <u>5.16</u> | 4.02  | 3.80     | 5.23  | 1.51       |
| Gross Margin              | 35%          | 36%         | 35%   | 41%      | 36%   | 37%        |
| Operating Margin          | 12%          | 13%         | 10%   | 13%      | 12%   | 10%        |
| ncome Before Tax margin   | 12%          | 14%         | 10%   | 11%      | 11%   | 12%        |

# Business Overview

### **Products Mix**



| Units: %      | 2016 | 2017 | 2018 | 2019 | 2020 | 2021 | Gross<br>Margin  |
|---------------|------|------|------|------|------|------|------------------|
| Trading       | 51   | 54   | 57   | 59   | 58   | 60   | Below<br>Average |
| Manufacturing | 49   | 46   | 43   | 41   | 42   | 40   | Above<br>Average |

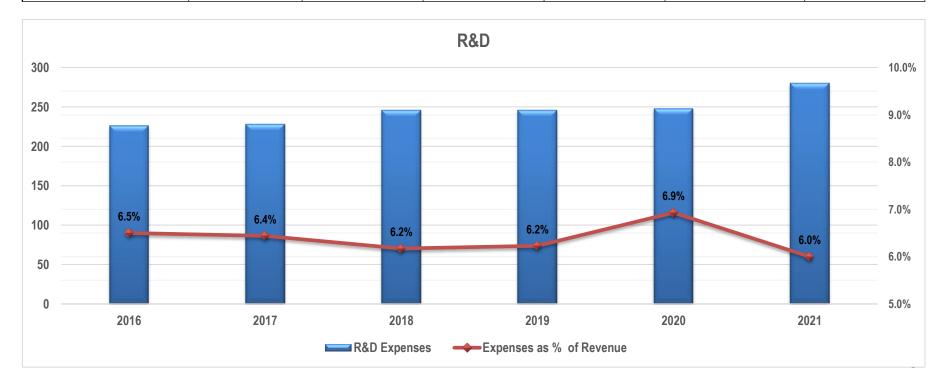


# Business Overview

# **R&D Expenses**



| Units: NT \$ M           | 2016 | 2017 | 2018 | 2019 | 2020 | 2021 |
|--------------------------|------|------|------|------|------|------|
| R&D Expenses             | 226  | 228  | 246  | 246  | 248  | 280  |
| Expenses as % of Revenue | 6.5% | 6.4% | 6.2% | 6.2% | 6.9% | 6.0% |

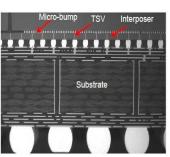


#### What We Do



- Industries which we serve:
  - Semiconductor (Front-End and Advanced Packaging)
  - Compound Semiconductor
  - LED / Mini LED / Micro LED
  - Flat Panel Display (TFT-LCD, AMOLED, Touch Panel)
  - Solar Cell / Battery
  - Biotech / Chemistry Analysis / Scientific Instrument,...











### Product and Technology





- Compound SEMI
- LED / Micro LED
- Flat Panel Display
- Solar Cell / Battery
- Biotech
- Scientific Inst.



- Wet-Process Tools
- Wafer Temporary Bonding **Debonding System**
- SEMI / Compound / LED

Representative / Distributor

Wafer Reclaim Service

- 12" Si Wafer
- 6" SiC Wafer

#### Wafer Reclaim Service



#### Scientech Corp.



- 12" Wafer Reclaim
  - Capacity: 120K→140K
     →160K/ Month
  - Cu and Non-Cu Process

SiC Post Slicing Process and Reclaim

• Capacity: 800 / Month



### **Wet Process Equipment**

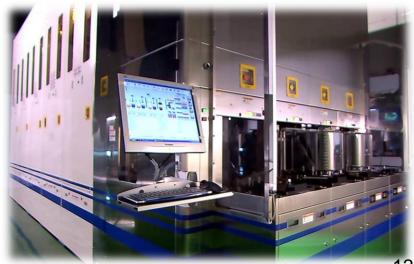


Scientech Corp.



- Wet-Bench / Single-Wafer Wet Process Equipment
- Applications:
  - Advanced Packaging Process
  - Semiconductor Front-End Process
  - Compound Semiconductor
  - Microelectromechanical Systems (MEMS)
  - High-End LED Fully-Automatic Advanced Process





# Temporary Bonding Debonding System



Scientech Corp.



- Temporary Bonding Debonding System (TBDB)
- Application: IGBT Power Device, Advanced Packaging for Semiconductor and LED
  - Temporary Bonding System
  - Temporary Debonding System
  - Release Layer Formation System
  - Carrier (Glass) Recycling System





### **Trading** (Agent/Distributor)





























Kensington

**Exclusive Agency** 

















Hirata

















**Supply Chain** 

**Partnership** 

#### Corporate Governance

### **ISO Certifications**



Initial Certification 2014/5/27

Valid Date:

2020/5/28 ~ 2023/5/27



Issue 4. Certified since 2010/3/24

Valid Date:

2019/4/30 ~ 2022/4/30



ISO14001

Issue 3. Certified since 2019/4/30

Valid Date:

2019/4/30 ~ 2022/4/30



ISO45001

Issue 1. Certified since 2019/11/20

Valid Date:

2019/11/20 ~ 2022/11/19



Issue 1. Certified since 2021/09/29

Valid Date:

2021/09/29 ~ 2024/09/28





**ISO27001** 

**Information Security** 



**ISO22301** 

**BCM** 



### Corporate Governance

# Intellectual Property Management (TIPS – AA) s





# Future Prospect

# The Growing Market



- Demand continues to grow: 5G, efficient computing, AI, IoT, AR, automotive electronics, cloud > etc.
- The continuous development of 12" semiconductor advanced process
  - Front-End: 5nm > 3nm > 2nm > 1nm
  - Advanced Packaging: Fan-Out \ WLCSP \ Flip-Chip \ 2.5D \ 3D \ etc.
- The continuous expansion of China semiconductor fabs in recent years
- The demand of 8" semiconductor fab is higher than the supplying capacity
- Compound semiconductor :
  - The investments of electrical car and 5G are growing tremendously
  - The third generation of semiconductor arises. The demand of high power and high frequency semiconductor are growing rapidly.
- The new application of Mini LED & Micro LED starts and it will lead the LED industry grows again.

# Q & A





Thank You!